S/N 09/941.125

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Gurtej Singh Sandhu et al.

Examiner: Arden B. Sperty

Serial No.:

09/941,125

Group Art Unit: 1775

Filed:

August 28, 2001

Docket: 303.676US5

0 3 2002

CHEMICAL VAPOR DEPOSITION OF TITANIUM

<u>AMENDMENT AND RESPONSE UNDER 37 CFR § 144</u>

Commissioner for Patents Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on February 15, 2002. Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is more previously pending claims 51, 53, 55, 56, 60, 66, 73, and 78. The specific amendments to COPY OF PAPERS ORIGINALLY FILED

- 51. (Amended) A via, comprising:
 - [a] an electrically conductive, nitride-free titanium alloy layer formed overlying walls and an exposed base layer of a contact hole; and
 - a fill coupled to the titanium alloy layer, wherein the fill comprises a metal selected from the group consisting of tungsten and aluminum.
- 53. (Amended) A via, comprising:
 - [a] an electrically conductive, nitride-free titanium alloy layer formed overlying walls and an exposed base layer of a contact hole, wherein the titanium alloy layer comprises titanium and an element selected from the group consisting of zinc, cadmium, mercury, aluminum, gallium, indium, tin, silicon, germanium, lead, arsenic and antimony; and
 - a fill coupled to the titanium alloy layer, wherein the fill comprises a metal selected from the group consisting of tungsten and aluminum.